

GPIHV7DK

N-channel 1200V 7A GaN Power HEMT in TO252 Package

Datasheet version 1.1: Preliminary

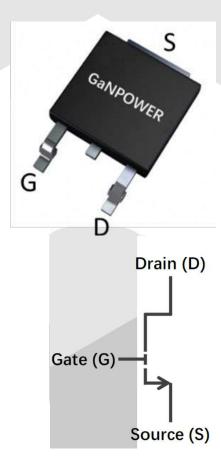
<u>Features</u>

BV _{dss}	R _{dson}	l _{ds}	Q _g
1200 V	158 mΩ	7 A	3.1 nC

- Ultra-low RDS(on)
- High dv/dt capability
- Extremely low input capacitance
- Zero Qrr
- Outstanding switching performance
- Low Profile

Applications

- Switching Power Applications
- Server and Telecom Power Application
- EVOBC and DC-DC Converters
- UPS, Inverters, PV



Description

These devices are N-channel 1200 V Power GaN HEMTs based on proprietary E-mode GaN on silicon technology. The resulting product has extremely low on state resistance, very low input capacitance and zero reverse recovery charge making it especially suitable for applications which require superior power density, ultra-high switching frequency and outstanding efficiency.



Device Characteristics

Sta	tatic Parameters Test da			ata			
	Parameters		Conditions	Min	Typical	Max	Unit
1	V _{gs(TH)}	Gate threshold voltage	V _{ds} =V _{gs} Id=2.5mA	1.2	1.4	1.7	V
2	BV _{dss}	Drain-Source breakdown voltage	V _{gs} =0V I _d < 14 μA (T=25 °C)		1200		V
3	l _{dss}	Zero gate voltage drain current, $T_C = 25^{\circ}C$	V _{gs} =0V V _{ds} =1200V		1.4	14	μА
4	lgss	Gate-Source Leakage	$V_{gs} = 6V$ $V_{ds} = 0V$		15	700	μΑ
5	R _{dson}	Static drain-source on resistance, $T_C = 25^{\circ}C$	V _{gs} =6V I _d =2.5A		158	250	mΩ
6	V_{sd}	Reverse conduction voltage	I _{sd} =1A V _{gs} =0V	1.50	2.50	3.0	V
7	R _g	Gate resistance	f=25Mhz Open drain		2.6		Ω
Dyr	Dynamic Parameters			Test data			
	Parameters		Conditions	Min	Typical	Max	Unit
	C _{iss}	Input capacitance	V _{gs} =0V		90		pf
1	C _{oss}	Output capacitance	V _{ds} =700V		27.2		pf
	C _{rss}	Reverse transfer capacitance	f=1MHz		4.9		pf
	Qg	Gate charge	V _{ds} =400V		3.1		nC
3	Q _{gs}	Gate to source charge	I _d =9A		0.5		nC
	Q _{gd}	Gate to drain charge	V _{gs} =6V		0.7		nC
2	Q _{rr}	Reverse recovery charge			0		nC
Swi	Switching Performance			Test data			
	Parameters		Conditions	Min	Typical	Max	Unit
1	t _{d(on)}	Turn-on delay time	V _{ds} =800V		6		ns
2	t _r	Rise time	I _d =2A		12		ns
3	t _{d(off)}	Turn-off delay time	R _g =22/2Ω		16		ns
4	t _f	Fall time	V _{gs} =-3/6V		12		ns



Absolute Max. Ratings

	Symbols	Parameters	Value	Unit
1	V_{DS-max}	Breakdown voltage transient @ T _{case} =25°C	1500	V
	V_{DS-max}	Breakdown voltage transient @ T _{case} =125°C	1250	V
2	V _{GS-max}	Gate to source max. voltage @ T _{case} =25°C	-12 to +7.5	V
3	I _{ds-max}	Drain to source DC current @ T _{case} =25°C	7	А
4	I _{ds-max}	Drain to source DC current @ T _{case} =100°C	5	А
5	dv/dt _{-max}	Drain to source voltage slew rate	150	V/ns
6	T_{J-max}	Max junction temperature	150	°C
7	$T_{S-storage}$	Storage temperature	-55 to 150	°C

Thermal and Soldering Characteristics (Typical)

	Symbols	Parameters	Value	Unit
1	R_{thJC}	Thermal resistance (junction to case)	1.25	°C /W
2	R_{thJA}	Thermal resistance (junction to ambient)	60	°C /W
2	T_{solder}	Reflow soldering temperature	260	°C

Ordering

Order Code	Package Type	Packaging Method	Qty
GPIHV7DK	TO-252		

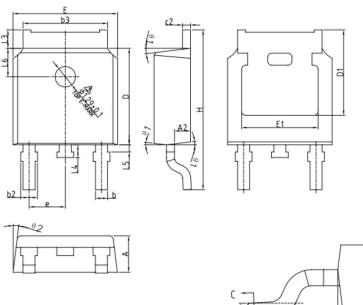


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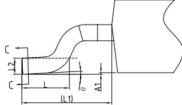
WWW. IGANPOWER.COM 230 -3410 LOUGHEED HWY VANCOUVER, BC, V5M 2A4 CANADA

BASE METAL

Package Information



PLATING

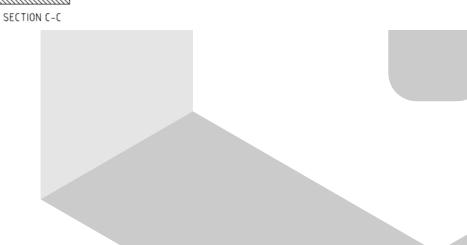


COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

	SYMBOL	MIN	NOM	MAX	
	Α	2.20	2.30	2.38	
	A1	0	-	0.10	
7	A2	0.90	1.01	1.10	
	Ь	0.72	-	0.85	
	b1	0.71	0.76	0.81	
	b2	0.72	_	0.90	
	b3	5.13	5.33	5.46	
	С	0.47	-	0.60	
	c1	0.46	0.51	0.56	
	c2	0.47	_	0.60	
	D	6.00	6.10	6.20	
	D1	5.25	1-	-	
	E	6.50	6.60	6.70	
	E1	4.70	1-	1	
	e	2.186	2.286	2.386	
	Н	9.80	10.10	10.40	
	L	1.40	1.50	1.70	
	L1		2.90REF		
	L2	0.51BSC			
	L3	0.90	-	1.25	
	L4	0.60	0.80	1.00	
	L5	0.15	1-1	0.75	
	L6	1.80REF			
	θ	0,	-	8'	
Δ	θ 1	5*	7*	9,	
A	θ 2	5*	7*	9.	

NOTES:

ALL DIMENSIONS REFER TO JEDEC STANDARD TO-252 AA DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.





Further Information

Important Notice-Unless expressly approved in writing by an authorized representative of GaNPower, GaNPopwer components are not designed, authorized or warranted for use in lifesaving, life sustaining, military, aircraft, or space applications, nor in products or systems where failure or malfunction may result in personal injury, death, or property or environmental damage. The information given in this document shall not in any event be regarded as a guarantee of performance. GaNPower hereby disclaims any or all warranties and liabilities of any kind, including but not limited to warranties of non-infringement of intellectual property rights. All other brand and product names are trademarks or registered trademarks of their respective owners. Information provided herein is intended as a guide only and is subject to change without notice. The information contained herein or any use of such information does not grant, explicitly, or implicitly, to any party any patent rights, licenses, or any other intellectual property rights. All rights reserved.

Data Source— Data here are based on recent tests but all parameters may not be up to date. Actual final test data from packaging production are available for selected customers upon request.

